

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	876	(monitor\$3 or detect\$3 or determin\$3) same product adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 09:33
L2	96	(monitor\$3 or detect\$3 or determin\$3) same product adj wafer with defect	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 09:33
L3	105	(monitor\$3 or detect\$3 or determin\$3) same product adj wafer with defect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 09:33
L4	23	(monitor\$3 or detect\$3 or determin\$3) same product adj wafer with defect\$3 and killer near4 defect	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 09:34
L5	6	(monitor\$3 or detect\$3 or determin\$3) same product near4 wafer with defect\$3 and killer near4 defect and (production near3 line or running near3 machine)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 09:48
L6	1	5 and (warn\$4 or alarm)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 09:35
L7	30	(monitor\$3 or detect\$3 or determin\$3 or inspect\$3) same product near6 wafer same defect\$3 and killer near4 defect and ((production or manufactur\$4) near3 line or running near3 machine)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:39
L8	2	7 and (warn\$4 or alarm)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:40
L9	1	7 and (correct\$3 with measur\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:41
L10	0	7 and (alert)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:42
L11	22	7 and (exceed\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:42

L12	0	7 and (defect near4 pre adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:43
L13	0	(defect near4 pre adj layer) with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:44
L14	1	(defect near4 pre adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:44
L15	85	(defect near4 underlayer)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:45
L16	1	7 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:47
L17	3	7 and classification with defect same database	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:48
L18	25	7 and classification with defect	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 11:48
L19	27	7 and (classification or classify\$3) with defect	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 12:14
L22	1421	250/307.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/02/02 12:52
L23	507	702/185.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/02/02 12:52
L24	1	22 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 12:54

L25	0	23 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 12:54
L26	1	23 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 12:54
L27	1	22 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/02/02 12:54
S1	281	702/34.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/02/02 09:32
S2	22403	((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and ((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or substrate\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:03
S3	12458	((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and (((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or substrate\$1) with (process\$3 or manufactur\$3 or fabricat\$3 or product\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 18:53
S4	7	S1 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 18:43
S5	9191	((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and (((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with (process\$3 or manufactur\$3 or fabricat\$3 or product\$3 or yield\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 18:55
S6	70	S5 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:18
S7	55	S6 and (defect\$1 with (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:06

S8	43	S6 and (defect\$1 near3 (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:19
S9	54	S5 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1 with defect\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:18
S10	32	S9 and (defect\$1 near3 (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:19
S11	2	S10 and (database with rule\$1 with (defect\$1 near2 type\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:22
S12	0	S5 and ((in adj line) with (automatic adj defect adj classification))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:24
S13	114	S5 and ((automatic adj defect adj classification))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:24
S14	0	S5 and ((automatic adj defect adj classification) same (in adj line))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:25
S15	9	S5 and ((automatic adj defect adj classification) and (in adj line))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:41
S16	0	S5 and (killer same (root with cause with analysis) same correct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:42
S17	21	S5 and ( (root with cause with analysis) same correct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:02
S18	1	S5 and ( (root with cause with analysis) same correct\$3) and (killer with defect\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/04 19:42

S19	290	(lin with long with hui) or( powerchip adj semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 09:36
S20	6	S19 and (defect with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 09:49
S21	0	("2005/0049836").URPN.	USPAT	OR	OFF	2005/04/08 09:37
S22	0	("2005/0049836").URPN.	USPAT	OR	OFF	2005/04/08 09:38
S23	0	("2003/0060916").URPN.	USPAT	OR	OFF	2005/04/08 09:40
S24	11	("20020034326"   "4618938"   "5761064"   "6016562"   "6246787"   "6477685"   "6559662"   "6583634"   "6628817"   "6703850"   "6757621").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/08 09:40
S25	81	("4618938").URPN.	USPAT	OR	OFF	2005/04/08 09:46
S26	81	("4618938").URPN.	USPAT	OR	OFF	2005/04/08 09:46
S27	0	("6828776").URPN.	USPAT	OR	OFF	2005/04/08 09:47
S28	13	S25 and (defect with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 09:50
S29	13	S26 and (defect with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 09:50
S30	281	702/34.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:00
S31	9195	((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and (((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with (process\$3 or manufactur\$3 or fabricat\$3 or product\$3 or yield\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:00
S32	71	S31 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:00
S33	55	S31 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1 with defect\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:01

S34	33	S33 and (defect\$1 near3 (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:01
S35	2	"5862055".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:02
S36	1216	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:03
S37	122	S36 and ((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and ((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or substrate\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/04/08 10:03